



P/N 96-208M50 QFP-to-PGA EIAJ 208-Position, 0.0197 [0.50] Pitch Adapter

FEATURES

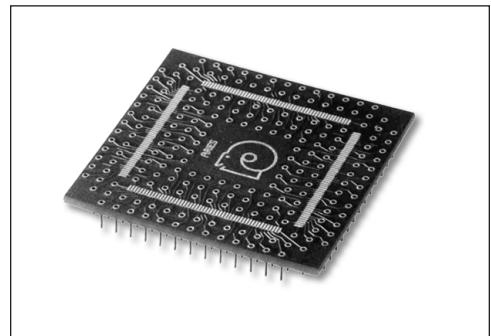
- Convert surface-mount QFP packages to a 17x17 PGA footprint.
- Reduce costs by using less-expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for Panelized Form or for mounting of consigned chips.

GENERAL SPECIFICATIONS

- ADAPTER BODY: FR-4 with 1-oz. Cu traces
- PADS: bare Cu protected with Entek® by Enthone or immersion white Sn to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- MALE PIN PLATING: 200 μ [5.08 μ] Sn/Pb 93/7 per ASTM B579-73 over 100 μ [2.54 μ] Ni per SAE AMS-QQ-N-29
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 ± 0.003 [0.71 ± 0.08] dia.
- Standard: will plug into PGA sockets



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

P/N 96-208M50

P/N 96-208M50-P for Panelized Form

P/N 208-PGM17039-30 for Wire Wrap PGA
Socket

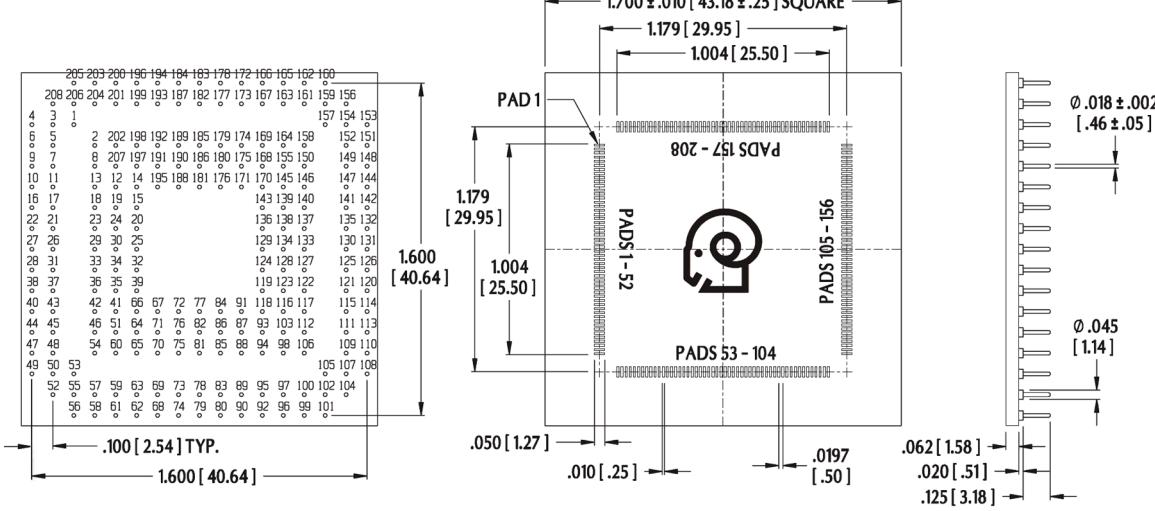
ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ± 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW ± 0.003 [± 0.08]

PIN-TO-PIN ± 0.003 [± 0.08] NON-CUMULATIVE

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



X-RAY VIEW TOP SIDE
QFP PAD ASSIGNMENT

TOP (QFP) SIDE



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